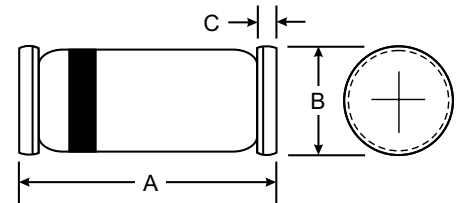

Features

- Silicon Planar Diodes
- Very low reverse current



Mechanical Data

- Case: SOD-80/LL34, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.05 grams (approx.)



LL34/ SOD-80		
Dim	Min	Max
A	3.30	3.70
B	1.30	1.60
C	0.28	0.50
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Test condition	Part	Symbol	Value	Unit
Reverse voltage		BAQ133	V _R	30	V
		BAQ134	V _R	60	V
		BAQ135	V _R	125	V
Peak forward surge current	t _p = 1 μs		I _{FSM}	2	A
Forward current			I _F	200	mA

Parameter	Test condition	Symbol	Value	Unit
Thermal resistance junction to ambient air	on PC board 50 mm x 50 mm x 1.6 mm	R _{thJA}	500	K/W
Junction temperature		T _j	175	°C
Storage temperature range		T _{stg}	- 65 to + 175	°C



Electrical Characteristics $T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 100\text{ mA}$		V_F			1	V
Reverse current	$E \leq 300\text{ lx}$, rated V_R		I_R		1	3	nA
	$E \leq 300\text{ lx}$, rated V_R , $T_j = 125\text{ }^{\circ}\text{C}$		I_R			0.5	μA
	$E \leq 300\text{ lx}$, $V_R = 15\text{ V}$	BAQ133	I_R		0.5	1	nA
	$E \leq 300\text{ lx}$, $V_R = 30\text{ V}$	BAQ134	I_R		0.5	1	nA
	$E \leq 300\text{ lx}$, $V_R = 60\text{ V}$	BAQ135	I_R		0.5	1	nA
Breakdown voltage	$I_R = 5\text{ }\mu\text{A}$, $t_p/T = 0.01$, $t_p = 0.3\text{ ms}$	BAQ133	$V_{(BR)}$	40			V
		BAQ134	$V_{(BR)}$	70			V
		BAQ135	$V_{(BR)}$	140			V
Diode capacitance	$V_R = 0$, $f = 1\text{ MHz}$		C_D			3	pF

Typical Characteristics ($T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

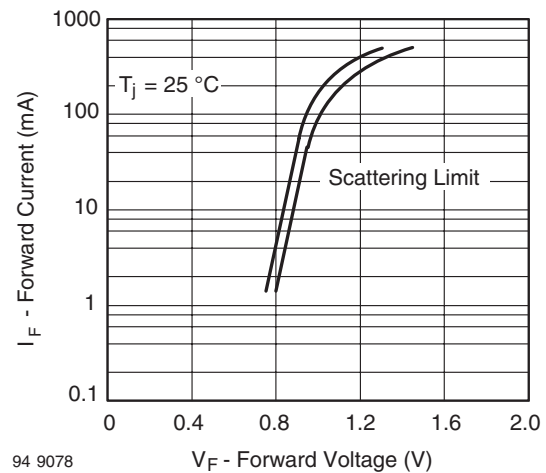
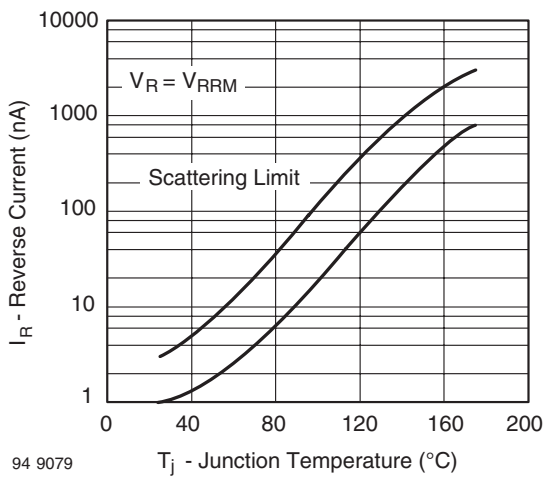


Figure 1. Reverse Current vs. Junction Temperature

Figure 2. Forward Current vs. Forward Voltage